

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Toshikazu Okubo et al.

Examiner: Khiem D. Nguyen

Serial No. 10/550,153

Art Unit: 2823

Filed: September 20, 2005 Confirmation No.: 1053

Title: Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product

RESPONSE TO OFFICE ACTION

Dear Examiner Nguyen:

This is a response to the Office Action dated January 5, 2009, which has a shortened statutory period for reply that ends on April 5, 2009. Please amend the above-identified application as follows.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 11 of this paper.